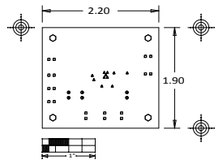
REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
A	INITIAL RELEASE	DIPANKAR	03/12/15

HARDWARE NAME:MAX17552AAUB_EVKIT_A
HARDWARE NUMBER:
ENGINEER:DIPANKAR MITRA DESIGNER:MANIKANDAN SELVAM
DATE: 03/09/2015 DDB++/GERBER: FAB_NOTES



IMPEDANCE TABLE				
LAYER	50 OHM	65 OHM	100 OHM TRACE / SPACE	75 OHM TRACE / SPACE
TOP	-	-	-	-
X	-	-	-	-
X	-	-	-	-
BOTTOM	-	-	-	-

NOTE: DO NOT EDIT THIS TABLE MANUALLY! USE IMPEDANCE TABLE GENERATOR FROM MAXIMTOOLS.

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (OZ)	DIELECTRIC THICKNESS (in.)	DIELECTRIC MATERIAL
1	TOP	2		FOIL
			TBD	FR4(RoHS)/EQIV
2	BOTTOM	2		FOIL

THE FINISHED PCB THICKNESS TO BE:	0.062" +/- 0.010"

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
A	12.0	+3.0/-10.0	PLATED	11	
B	39.37	+3.0/-3.0	PLATED	18	
C	45.28	+3.0/-3.0	PLATED	6	
D	125.0	+3.0/-3.0	PLATED	4	

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).

MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)

2. BOARD MATERIAL:
   - (X) FR4 (RoHS COMPLIANT) OR EQUIVALENT
   - ( ) ISOLA-FR408HR
   - ( ) NELCO-4000-13 OR EQUIVALENT
   - ( ) 370HR (RoHS COMPLIANT) OR EQUIVALENT
   - ( ) ROGERS 4350B
   - ( ) ROGERS 4003C
   - ( ) OTHER _____
3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATING OF 94V-O.
5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH. BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.

TOOLING: (USE CHECKED ITEMS FOR TOOLING)

7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER RS274X OR ODB++ FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNC DRILL FILE.
8. IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.
9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
   - ( ) FILLETED
   - (X) NOT FILLETED
10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES. LEGEND TO LEGEND +/- 0.007 INCHES

FINISH: (USE CHECKED ITEMS FOR PLATING)

11. PLATING SPECIFICATION:
    - ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS CAN BE (0.5 OZ), THE FINISH COPPER WEIGHT IS (1 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ) UNLESS OTHERWISE SPECIFIED
    - ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ), THE FINISH COPPER WEIGHT IS (2 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ). UNLESS OTHERWISE SPECIFIED
    - (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ), THE FINISH COPPER WEIGHT IS (2 OZ)MINIMUM. FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (<2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ). UNLESS OTHERWISE SPECIFIED
    - ( ) OTHER _____
12. CHECK ALL THAT APPLY
    - ( ) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
    - (X) LEAD FREE AND RoHS COMPLIANT OR EQUIVALENT LEAD FREE PLATING
    - ( ) ELECTODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (KNOOP HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C. GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0, CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-600 MICROINCHES THICK).
    - ( ) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
    - ( ) FINGERS TO BE GOLD PLATED.
    - ( ) OTHER _____
13. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP. MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING.
14. CHECK ALL THAT APPLY
    - (X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI) PER ARTWORK.
    - ( ) GREEN TAIYO PSR-4000
    - ( ) OTHER _____
15. CHECK ALL THAT APPLY
    - (X) APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY BASED INK PER ARTWORK.
    - ( ) OTHER _____
16. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE) THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.

MISCELLANEOUS:

19. FOR ALL DRILL INFORMATION REFER TO DRILL CHART.
    - ( ) NON-CONDUCTIVE EPOXY. FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
    - ( ) SILVER. FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
20. IF PRESENT. ALL MICRO-VIAS LESS THAN 0.006 INCHES FHS WHEN USED AS VIP (VIA IN PAD) OR STACKED TO BE PLATED SHUT WITH COPPER, UNLESS OTHERWISE SPECIFIED.
21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS. SCRATCHES PROBE MARKS OR OTHER DEFORMITIES THAT COULD EFFECT THE APPERANCE AND PERFORMACE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.
22. THIEVING:
    - ( ) SUPPLIER MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
    - (X) SUPPLIER MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
23. PEMNUT
    - ( ) PEMNUTS TO BE INSTALLED BY SUPPLIER.
    - ( ) PEMNUTS NOT TO BE INSTALLED BY SUPPLIER.
    - (X) NOT APPLICABLE

TOLERANCES UNLESS OTHERWISE SPECIFIED

FRACTIONS +/- 1/16 | DECIMALS .XX +/- .01, .XXX +/- .005 | ANGLES +/- 1/2°

MATERIAL: SEE NOTES

FINISH: SEE NOTES

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DRAWN BY:MANIKANDAN	DATE: 03/12/15
CHECKED BY: NAGARAJ	DATE: 03/12/15
APPR. BY: DIPANKAR	DATE: 03/12/15
APPR. BY:	DATE:

maxim integrated™

HARDWARE NAME: MAX17552AAUB_EVKIT_A

HARDWARE NUMBER: XX-XXXXX-XXX REV A

NOT TO SCALE | TEMPLATE REV: | SHEET 1 OF 1